

PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	Bill of Sale
CONVEYING PARTY DATA	
Name	Execution Date
Stablcor, Inc.	05/05/2010
RECEIVING PARTY DATA	
Name:	James D. Dodson
Street Address:	17011 Beach, #900
City:	Huntington Beach
State/Country:	CALIFORNIA
Postal Code:	92647
Name:	Thomas R. Carson
Street Address:	17011 Beach, #900
City:	Huntington Beach
State/Country:	CALIFORNIA
Postal Code:	92647
Name:	Doug S. Schneider
Street Address:	17011 Beach, #900
City:	Huntington Beach
State/Country:	CALIFORNIA
Postal Code:	92647
PROPERTY NUMBERS Total: 6	
Property Type	Number
Patent Number:	6869664
Patent Number:	7667142
Patent Number:	7635815
Patent Number:	7301105
Patent Number:	7730613

OP \$240.00 6869664

501542893

PATENT
REEL: 026331 FRAME: 0916

Application Number:

11879256

CORRESPONDENCE DATA

Fax Number: (949)852-0004

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 949.852.0000

Email: pto@kppb.com

Correspondent Name: David J. Bailey

Address Line 1: 2875 Michelle Drive

Address Line 2: Suite 110

Address Line 4: Irvine, CALIFORNIA 92606

NAME OF SUBMITTER:

Trudi Thompson

Total Attachments: 7

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BILL OF SALE

FOR GOOD AND VALUABLE CONSIDERATION, receipt of which is hereby acknowledged, StablcOR, Inc., a California corporation (the "Seller"), has hereby granted, sold, assigned, transferred, conveyed, and delivered and does by these presents grant, sell, assign, transfer, convey, and deliver unto James D. Dodson, Thomas R. Carson, and Doug S. Schneider (collectively, the "Buyers") all of Seller's right, title and interest in and to assets described in Exhibit A (the "Assets"). Seller further agrees, without further consideration, to cause to be performed such lawful acts and to execute such further documents as Buyers may reasonably request, to fully effectuate this sale.

This Bill of Sale is binding upon and inures to the benefit of Seller and Buyers and their respective heirs, executors, administrators, successors and assigns. This Bill of Sale may be executed in two or more counterparts, each of which shall be deemed an original, but all of which together shall constitute one and the same instrument.

IN WITNESS WHEREOF, the parties have executed this Bill of Sale on March 18, 2010.

SELLER:

STABLCOR, INC.,
a California corporation


By: Don Roy
Its: President

BUYERS:

JAMES D. DODSON,
an individual


By: James D. Dodson

THOMAS R. CARSON,
an individual


By: Thomas R. Carson

DOUG S. SCHNEIDER,
an individual


By: Doug S. Schneider

5-11-2010

EXHIBIT A

LIST OF ASSETS

- 1) The toll-free telephone number (714) 524-1188 and all directory listings.
- 2) The "Stablcor" trademark.
- 3) All rights, title and interest in any and all intellectual property of Stablcor relating to the <http://stablcor.com> domain, including all client and subscriber lists, all branding and trademarks, all domain names and URL's, all existing content and HTML files, and all products and proceeds of the foregoing in any form whatsoever and wheresoever located.
- 4) All Stablcor furniture, fixtures, and computer equipment, including, but not limited to:
 - a. One desk;
 - b. Three chairs;
 - c. Two bookshelves;
 - d. Six filing cabinets;
 - e. Six framed pictures;
 - f. One desktop computer;
 - g. One computer monitor; and
 - h. One computer printer.

EXHIBIT A

U.S. PATENTS AND PATENT APPLICATIONS

1. United States Patent No. US6,869,664 Issued on MARCH 22, 2005 Entitled "LIGHT WEIGHT CIRCUIT BOARD WITH CONDUCTIVE CONSTRAINING CORES"
2. U.S. Patent Application No. 10/921,616 Entitled "LIGHT WEIGHT CIRCUIT BOARD WITH CONDUCTIVE CONSTRAINING CORES" filed on August 18, 2004.
3. U.S. Patent Application No. 10/921,649 Entitled "LIGHT WEIGHT CIRCUIT BOARD WITH CONDUCTIVE CONSTRAINING CORES" filed on August 18, 2004.
4. U.S. Divisional Patent Application No. 12/171,658 Entitled "PRINTED WIRING BOARD WITH CONDUCTIVE CONSTRAINING CORE INCLUDING RESIN FILLED CHANNELS" filed on July 11, 2008.
5. U.S. Provisional Patent Application No. 60/571,284 Entitled "METHOD OF DATA PREPARATION FOR PRINTED WIRING BOARD WITH CONDUCTIVE CONSTRAINING CORE" filed on MAY 15, 2004.
6. U.S. Provisional Patent Application No. 60/653,258 Entitled "METHOD OF 1UP DATA PREPARATION FOR PRINTED WIRING BOARD WITH CONDUCTIVE CONSTRAINING CORE" filed on FEBRUARY 15, 2005.
7. U.S. Provisional Patent Application No. 60/662,162 Entitled "PANELIZATION PROCESS FOR PRINTED WIRING BOARD WITH CONDUCTIVE CONSTRAINING CORE" filed on MARCH 15, 2005.
8. United States Patent No. US7,301,105 Issued on NOVEMBER 27, 2007 Entitled "PWB INCLUDING LAYERS FORMED BY BASE AND INSERT MATERIALS POSSESSING DIFFERENT PHYSICAL PROPERTIES"
9. U.S. Patent Application No. 11/376,806 Entitled "MANUFACTURING PROCESS: HOW TO CONSTRUCT CONSTRAINING CORE MATERIAL INTO PWB" filed on MARCH 15, 2006.

10. U.S. Provisional Patent Application Entitled "MANUFACTURING PROCESS: HOW TO FILL CLEARANCE HOLES AND SLOTS OF CONDUCTIVE CONSTRAINING CORE USED INTO PWB" filed on MARCH 6, 2006.
11. U.S. Patent Application No. 11/682,860 Entitled "PROCESS FOR MANUFACTURING PRINTED WIRING BOARDS POSSESING ELECTRICALLY CONDUCTIVE CONSTRAINING CORES" filed on MARCH 6, 2007.
12. U.S Patent Application No. 11/879,256 Entitled "BUILD-UP PRINTED WIRING BOARD SUBSTRATE HAVING A CORE LAYER THAT IS PART OF A CIRCUIT" filed on JULY 16, 2007.
13. United States Patent No. US7, 173,325 Entitled "EXPANSION CONSTRAINED DIE STACK" issued on FEBRUARY 6, 2007.

FOREIGN PATENTS AND PATENT APPLICATIONS

1. European Patent No. EP1360067, Issued on JANUARY 29, 2007 Entitled "LIGHTWEIGHT CIRCUIT BOARD WITH CONDUCTIVE CONSTRAINING CORES"
2. GERMAN Patent No. DE601,268,32T, Issued on NOVEMBER 15, 2007 Entitled "LIGHTWEIGHT CIRCUIT BOARD WITH CONDUCTIVE CONSTRAINING CORES"
3. PCT Patent Application No. PCT/US01/48199 Entitled "LIGHTWEIGHT CIRCUIT BOARD WITH CONDUCTIVE CONSTRAINING CORES" filed on DECEMBER 11, 2001.
4. MALAYSIA National Phase Patent Application No. 90015654 Entitled "LIGHTWEIGHT CIRCUIT BOARD WITH CONDUCTIVE CONSTRAINING CORES" filed on DECEMBER 12, 2001.
5. TAIWAN National Phase Patent Application No. 90130820 Entitled "LIGHTWEIGHT CIRCUIT BOARD WITH CONDUCTIVE CONSTRAINING CORES" filed on DECEMBER 12, 2001.
6. CHINA National Phase Patent Application No. 01821947.0 Entitled "LIGHTWEIGHT CIRCUIT BOARD WITH CONDUCTIVE CONSTRAINING CORES" filed on DECEMBER 11, 2001.
7. JAPAN National Phase Patent Application No. 2002-549457 Entitled "LIGHTWEIGHT CIRCUIT BOARD WITH CONDUCTIVE CONSTRAINING CORES" filed on DECEMBER 11, 2001.
8. INDIA Patent No. 231595 Entitled "LIGHTWEIGHT CIRCUIT BOARD WITH CONDUCTIVE CONSTRAINING CORES" filed on DECEMBER 11, 2001. Granted on June 03, 2009
9. PCT Patent Application No. PCT/US2005/017150 Entitled "PRINTED WIRING BOARD WITH CONDUCTIVE CONSTRAINING CORE INCLUDING RESIN FILLED CHANNELS" filed on MAY 16, 2005.
10. TAIWAN National Phase Patent Application No. 94115763 Entitled "PRINTED WIRING BOARD WITH CONDUCTIVE CONSTRAINING CORE INCLUDING RESIN FILLED CHANNELS" filed on MAY 16, 2005.

11. KOREA National Phase Patent Application No. 10-2006-7024755 Entitled "PRINTED WIRING BOARD WITH CONDUCTIVE CONSTRAINING CORE INCLUDING RESIN FILLED CHANNELS" filed on NOVEMBER 24, 2006.
12. CHINA National Phase Patent Application No. 200580015588.7 Entitled "PRINTED WIRING BOARD WITH CONDUCTIVE CONSTRAINING CORE INCLUDING RESIN FILLED CHANNELS" filed on MAY 16, 2005.
13. EUROPE National Phase Patent Application No. EP 1 754 398 Entitled "PRINTED WIRING BOARD WITH CONDUCTIVE CONSTRAINING CORE INCLUDING RESIN FILLED CHANNELS".
14. JAPAN National Phase Patent Application No. 2007-513474 Entitled "PRINTED WIRING BOARD WITH CONDUCTIVE CONSTRAINING CORE INCLUDING RESIN FILLED CHANNELS" filed on MAY 16, 2005.
15. HONGKONG National Phase Patent Application No. 8108996.9 Entitled "PRINTED WIRING BOARD WITH CONDUCTIVE CONSTRAINING CORE INCLUDING RESIN FILLED CHANNELS" filed on MAY 16, 2005
16. PCT Patent Application No. PCT/US2005/030709 Entitled "PWB INCLUDING LAYERS FORMED BY BASE AND INSERT MATERIALS POSSESSING DIFFERENT PHYSICAL PROPERTIES" filed on AUGUST 29, 2005.
17. PCT Patent Application No. PCT/US2006/009597 Entitled "MANUFACTURING PROCESS: HOW TO CONSTRUCT CONSTRAINING CORE MATERIAL INTO PWB" filed on MARCH 15, 2006.
18. EUROPE National Phase Patent Application No. 6738663.4 Entitled "MANUFACTURING PROCESS: HOW TO CONSTRUCT CONSTRAINING CORE MATERIAL INTO PWB" filed on MARCH 15, 2006.
19. KOREA National Phase Patent Application No. 10-2007-7023589 Entitled "MANUFACTURING PROCESS: HOW TO CONSTRUCT CONSTRAINING CORE MATERIAL INTO PWB" filed on MARCH 15, 2006.
20. CHINA National Phase Patent Application No. 200680015678.0 Entitled "MANUFACTURING PROCESS: HOW TO CONSTRUCT CONSTRAINING CORE MATERIAL INTO PWB" filed on MARCH 15, 2006.

21. JAPAN National Phase Patent Application Entitled "MANUFACTURING PROCESS: HOW TO CONSTRUCT CONSTRAINING CORE MATERIAL INTO PWB" filed on MARCH 15, 2006.
Exhibit A
22. PCT Patent Application No. US2007/063429 Entitled "PROCESS FOR MANUFACTURING PRINTED WIRING BOARDS POSSESING ELECTRICALLY CONDUCTIVE CONSTRAINING CORES" filed on MARCH 6, 2007.
23. KOREA National Phase Patent Application No. 10-2008-7024427 Entitled "PROCESS FOR MANUFACTURING PRINTED WIRING BOARDS POSSESING ELECTRICALLY CONDUCTIVE CONSTRAINING CORES" filed on OCTOBER 6, 2008.
24. CHINA National Phase Patent Application No. 200780016293 Entitled "PROCESS FOR MANUFACTURING PRINTED WIRING BOARDS POSSESING ELECTRICALLY CONDUCTIVE CONSTRAINING CORES" filed on NOVEMBER 5, 2008.
25. JAPAN National Phase Patent Application No. 2008-558512 Entitled "PROCESS FOR MANUFACTURING PRINTED WIRING BOARDS POSSESING ELECTRICALLY CONDUCTIVE CONSTRAINING CORES" filed on NOVEMBER 5, 2008.
26. PCT Patent Application No. PCT/US07/16210 Entitled "BUILD-UP PRINTED WIRING BOARD SUBSTRATE HAVING A CORE LAYER THAT IS PART OF A CIRCUIT" filed on JULY 16, 2007.
27. TAIWAN National Phase Patent Application No. 96133163 Entitled "BUILD-UP PRINTED WIRING BOARD SUBSTRATE HAVING A CORE LAYER THAT IS PART OF A CIRCUIT" filed on SEPTEMBER 7, 2007.
28. CHINA National Phase Patent Application No. 200780031170.4 Entitled "BUILD-UP PRINTED WIRING BOARD SUBSTRATE HAVING A CORE LAYER THAT IS PART OF A CIRCUIT" filed on SEPTEMBER 7, 2007.
29. JAPAN National Phase Patent Application No. PCT/US07/16210 Entitled "BUILD-UP PRINTED WIRING BOARD SUBSTRATE HAVING A CORE LAYER THAT IS PART OF A CIRCUIT" filed on SEPTEMBER 7, 2007.